Technology of Integrated Circuits and Microsystems (E031420)

Course Specifications
Valid as from the academic year 2016-2017

Course

Lecturers in academic year 2016-2017

Bosman, Erwin
Vanfleteren, Jan

Course offerings and teaching methods in academic year 2016-2017

B (semester 1)
lecture 30.0 h
project 30.0 h

A (semester 1)
project 30.0 h
guided self-study 30.0 h

Offered in the following programmes in 2016-2017

Bridging Programme Master of Science in Electrical Engineering (main subject Electronic Circuits and Systems)
Master of Science in Electrical Engineering (main subject Electronic Circuits and Systems)
Master of Science in Biomedical Engineering
International Master of Science in Biomedical Engineering
Master of Science in Biomedical Engineering
Master of Science in Electrical Engineering
Master of Science in Engineering Physics
Master of Science in Engineering Physics

Teaching languages
Dutch, English

Keywords
cmos, fabrication, mems, microsystems, technology, PCB

Position of the course
The purpose of this course is to acquaint students with the various technologies for the realization of integrated circuits, printed circuit boards, microfluidic systems and microelectromechanical systems (MEMS). First, the different fabrication technologies are described that serve as the basis for any advanced micro-and nanotechnology (deposition, lithography, etching ...), followed by the realization of different microsystem components (cmos chips, microfluidic components, MEMS and chip packages) and interconnection systems (printed circuit boards, flexible and stretchable electronics)

Contents

• Basic technology steps: deposition, lithography, etching, laserstructuring, ...
• Microsystem components: cmos chips, microfluidic components, MEMS and chip packages
• Advanced integrated microsystems: electrical PCB's, optical PCB's, flexible & stretchable microsystems
• Practicum polymer microsystems: fabrication and characterization
• Literature paper study

Initial competences

(Course)

(Approved) 1
Basic knowledge physics, chemistry and electronics

**Final competences**
1. detailed knowledge on microsystems process steps
2. basic knowledge on different types of microsystems
3. insight in the physics of microfabrication
4. practical experience on the characterization of microfeatures
5. practical experience in cleanroom laboratories
6. analysis and synthesis of a scientific article
7. writing of a scientific report

**Conditions for credit contract**
Access to this course unit via a credit contract is determined after successful competences assessment

**Conditions for exam contract**
This course unit cannot be taken via an exam contract

**Teaching methods**
Guided self-study, lecture, project

**Extra information on the teaching methods**
Classroom lectures; Projects

**Learning materials and price**
handouts of class room lecture presentations; selected scientific publications for selfstudy

**References**

**Course content-related study coaching**
Personal contact with 3 scientific researchers and interactive support through the Minerva-portal

**Evaluation methods**
end-of-term evaluation

**Examination methods in case of periodic evaluation during the first examination period**
Open book examination, oral examination, report

**Examination methods in case of periodic evaluation during the second examination period**
Open book examination, oral examination, report

**Examination methods in case of permanent evaluation**

**Possibilities of retake in case of permanent evaluation**
not applicable

**Extra information on the examination methods**
During examination period: evaluation of graded project reports, understand and explain 1 scientific article, explain course material using handouts (open book)

**Calculation of the examination mark**
Evaluation during examination period
In case of unauthorized absence during the practicum, the student is obliged to join a later practicum session, if a later session is taking place. If not, the student will receive a 0-score for the practicum report

(Approved)